* Please submit this form by **11 August 2017** to Angeline Tan at email: comsol.conference@i-math.com.sg.
* [Click here to view **Submission Abstract Guidelines**](http://www.imath-asia.com/Events/2017/COMSOL_Conference/COMSOL_Conference_2017_Abstract_Guidelines.pdf).

*Form will only be accepted if all the mandatory fields (*\**) are filled up.*

|  |
| --- |
| **PERSONAL INFORMATION**  |
| **Full Name**\*Click or tap here to enter text. |
| **Email**\*Click or tap here to enter text. | **How would you like to present at the conference? \***[ ]  Oral Presentation[ ]  Poster Presentation |
| **TITLE** (not to exceed 100 characters)\* |
|  |
| **DETAILED ABSTRACT** (not to exceed 500 words) \* |
|  |
| **Image, Caption** (Please provide an image and a short caption to represent your work.) |
| Insert caption here |

**Which of these application areas are related to your submitted work? (select up to three) \***

[ ]  AC/DC Electromagnetics

[ ]  Acoustics and Vibrations

[ ]  Batteries, Fuel Cells, and Electrochemical Processes

[ ]  Bioscience and Bioengineering

[ ]  Chemical Reaction Engineering

[ ]  Computational Fluid Dynamics

[ ]  Electromagnetic Heating

[ ]  Geophysics and Geomechanics

[ ]  Heat Transfer and Phase Change

[ ]  MEMS and Nanotechnology

[ ]  Microfluidics

[ ]  Multiphysics

[ ]  Optics, Photonics and Semiconductors

[ ]  Optimization and Inverse Methods

[ ]  Particle Tracing

[ ]  Piezoelectric Devices

[ ]  Plasma Physics

[ ]  RF and Microwave Engineering

[ ]  Simulation Methods and Teaching

[ ]  Structural Mechanics and Thermal Stresses

[ ]  Transport Phenomena

**Which COMSOL products did you use in your work? \***

[ ]  AC/DC Module

[ ]  Acoustics Module

[ ]  Application Builder

[ ]  Batteries & Fuel Cells Module

[ ]  CAD Import Module

[ ]  CFD Module

[x]  COMSOL Multiphysics®

[ ]  COMSOL Server™

[ ]  Chemical Reaction Engineering Module

[ ]  Corrosion Module

[ ]  Design Module

[ ]  ECAD Import Module

[ ]  Electrochemistry Module

[ ]  Electrodeposition Module

[ ]  Fatigue Module

[ ]  File Import for CATIA® V5

[ ]  Geomechanics Module

[ ]  Heat Transfer Module

[ ]  LiveLink™ for AutoCAD®

[ ]  LiveLink™ for Excel®

[ ]  LiveLink™ for Inventor®

[ ]  LiveLink™ for MATLAB®

[ ]  LiveLink™ for PTC® Creo® Parametric™

[ ]  LiveLink™ for PTC® Pro/ENGINEER®

[ ]  LiveLink™ for Revit®

[ ]  LiveLink™ for SOLIDWORKS®

[ ]  LiveLink™ for Solid Edge®

[ ]  MEMS Module

[ ]  Material Library

[ ]  Microfluidics Module

[ ]  Mixer Module

[ ]  Molecular Flow Module

[ ]  Multibody Dynamics Module

[ ]  Nonlinear Structural Materials Module

[ ]  Optimization Module

[ ]  Particle Tracing Module

[ ]  Pipe Flow Module

[ ]  Plasma Module

[ ]  RF Module

[ ]  Ray Optics Module

[ ]  Rotordynamics Module

[ ]  Semiconductor Module

[ ]  Structural Mechanics Module

[ ]  Subsurface Flow Module

[ ]  Wave Optics Module

**IMPORTANT**

* By submitting this form, I agree to these terms & conditions\*

By submitting abstracts, full length papers, presentations, movies, model files and other materials ("Contributed Materials") through this website, via email or at the COMSOL Conference 2017 Singapore to i-Math Pte Ltd and/or its principal COMSOL AB (collectively, Organizer), whether submission is made at this time or at a later time, you hereby grant the Organizer a nonexclusive, royalty-free, perpetual, worldwide, and unrestricted license to use, copy, publicly display, and prepare derivative works of the Contributed Materials, in whole or in part, and to distribute the Contributed Materials and derivative works thereof, in whole or in part, as part of the COMSOL Conference materials and proceedings and otherwise. Such license includes the right to reproduce the Contributed Materials and derivative works thereof in hard copy or electronic form, to archive the Contributed Materials and derivative works thereof on one or more of the Organizer’s websites and to distribute the Contributed Materials and derivative works thereof in any manner. You hereby represent and warrant that you have sufficient rights and/or authorization to grant the Organizer the rights provided herein, including authorization with respect to any Contributed Materials in which your employer has any right, title, or interest, and that none of the Contributed Materials infringes any intellectual property, proprietary, or other third party rights. Additionally, you hereby represent and warrant that you will only use a valid license for which you are an authorized user for the COMSOL Multiphysics® software according to the terms of the COMSOL Software License Agreement in connection with your Contributed Materials. You shall retain all ownership rights to the copyrights in the Contributed Materials and in view of the fact that the license granted to the Organizer is nonexclusive, there are no limits on your right to publish and distribute such Contributed Materials. The Organizer agrees that it will provide attribution for all Contributed Materials to the respective authors. This Agreement contains the entire understanding of the parties with respect to the subject matter, and supersedes all prior, contemporaneous, and subsequent proposals, agreements, representations, and understandings, with the exception of the COMSOL Software License Agreement, which shall govern the use of any software made available during the COMSOL Conference. This Agreement may not be changed except as provided herein in a writing signed by you and us.